



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape
☒	1	0,700mm (27,56mil)	PTH	Round	1 - 4	Via	Rounded
▽	3	0,762mm (30,00mil)	PTH	Round	1 - 4	Pad	Rounded
☒	6	0,800mm (31,50mil)	PTH	Round	1 - 4	Pad	Rounded
☒	8	0,914mm (36,00mil)	PTH	Round	1 - 4	Pad	(Mixed)
○	8	1,422mm (56,00mil)	PTH	Round	1 - 4	Pad	(Mixed)
◊	12	0,508mm (20,00mil)	PTH	Round	1 - 4	Via	Rounded
☒	12	3,850mm (151,58mil)	PTH	Round	1 - 4	Via	Rounded
□	16	1,400mm (55,12mil)	PTH	Round	1 - 4	Pad	Rounded
○	18	1,100mm (43,31mil)	PTH	Round	1 - 4	(Mixed)	Rounded
⊕	68	1,000mm (39,37mil)	PTH	Round	1 - 4	(Mixed)	(Mixed)
▽	160	0,965mm (38,00mil)	PTH	Round	1 - 4	Pad	(Mixed)
□	286	0,300mm (11,81mil)	PTH	Round	1 - 4	Via	Rounded
☒	7971	0,350mm (13,78mil)	PTH	Round	1 - 4	Via	Rounded
8569 Total							

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0,020mm	4	
1	1		0,035mm		
	Dielectric 1	2116	0,130mm	4.45	
2	Signal Layer 1		0,035mm		
	Dielectric 3		1,130mm	4.74	
3	Signal Layer 2		0,035mm		
	Dielectric 2	2116	0,130mm	4.45	
4	4		0,035mm		
	Bottom Solder	Solder Resist	0,020mm	4	
	Bottom Overlay				

MATIERE FR4
CUIVRE (voir empilage)
SERIGRAPHIE BLANCHE 2
FACES
VERNIS VERT SELECTIF 2 FACES
FINITION NiAu

Radio Oceanography Laboratory				
	Indice	Modification	Date	Dessine par
Edition :		CARTE LO-BACKPLANE-2024		
Dessinateur : RONVEL		PLAN DE PERCAGE		
Date : 15-12-2024		Folio : 1/1		
Ind				